

This listing of claims will replace all prior versions and listing of claims in the application.

Listing of Claims:

Claim 1 (withdrawn): A polishing article for the electrochemical mechanical polishing (ECMP) of a workpiece, said article comprising an electrically-conductive compound which is formed into a layer, said compound comprising an admixture which comprises:

- (a) a polymeric component forming a continuous phase in said layer; and
- (b) an electrically-conductive filler component forming a first discrete phase within said continuous phase,

whereby, with the workpiece and the layer being electrically connected and with an electrical bias being applied between the workpiece and layer, the bias being capable of activating an electrochemical reaction, the compound exhibiting an overpotential for the activation of said reaction greater than said bias.

Claim 2 (withdrawn): The polishing article of claim 1 wherein said overpotential is at least about 1 V.

Claim 3 (withdrawn): The polishing article of claim 1 wherein said electrically-conductive filler component is selected from the group consisting of graphite particles, metal particles, metal-coated metal particles, metal-coated non-metal particles, and mixtures thereof.

Claim 4 (withdrawn): The polishing article of claim 1 wherein said electrically-conductive filler component comprises graphite particles.

Claim 5 (withdrawn): The polishing article of claim 1 wherein said electrically-conductive filler component comprises tin particles.

Claim 6 (withdrawn): The polishing article of claim 1 wherein said polymeric component comprises a urethane polymer or copolymer.

Claim 7 (withdrawn): The polishing article of claim 1 wherein the compound comprises, by total weight of the components (a) and (b), between about 25-95% of the electrically-conductive filler component.

Claim 8 (withdrawn): The polishing article of claim 1 wherein the electrically-conductive filler component comprises particles having a mean average particle size of between about 0.01-10 mil (0.25-250 μm).

Claim 9 (withdrawn): The polishing article of claim 1 wherein the compound has an electrical volume resistivity of not greater than about 1 $\Omega\text{-cm}$.

Claim 10. (withdrawn): The polishing article of claim 1 wherein the admixture further comprises:

(c) a resin filler component forming a second discrete phase within said continuous phase, said second discrete phase being substantially free of said electrically-conductive filler component.

Claim 11 (withdrawn): The polishing article of claim 10 wherein the compound comprises, by total weight of the components (a), (b), and (c), between about 1-10% of the resin filler component.

Claim 12 (withdrawn): The polishing article of claim 10 wherein the resin filler component comprises particles having a mean average particle size of between about 0.08-2 mil (2-50 μm).

Claim 13 (withdrawn): The polishing article of claim 10 wherein said resin filler component comprises particles of one or more thermoplastic resins.

Claim 14 (withdrawn): The polishing article of claim 1 wherein said article further comprises a carrier, said layer of said electrically-conductive compound being supported on said carrier.

Claim 15 (withdrawn): The polishing article of claim 14 wherein said carrier comprises a sheet of an electrically-conductive mesh.

Claim 16 (withdrawn): An electrochemical mechanical polishing (ECMP) system for processing a workpiece, said system comprising:

a polishing article electrically connected to the workpiece, the article comprising an electrically-conductive compound which is formed into a layer, said compound comprising an admixture which comprises:

(a) a polymeric component forming a continuous phase in said layer; and
(b) an electrically-conductive filler component forming a first discrete phase within said continuous phase,
a workpiece electrically connected to the layer; and
an electrical bias applied between the workpiece and the layer,
whereby, with the electrical bias applied between the workpiece and the layer being capable of activating an electrochemical reaction, the compound exhibiting an overpotential for the activation of said reaction greater than said bias.

Claim 17 (withdrawn): The ECMP system of claim 16 wherein the layer has a processing surface and the workpiece has a workpiece surface disposed against the processing surface of the layer.

Claim 18 (withdrawn): The ECMP system of claim 16 wherein said overpotential is at least about 1 V.

Claim 19 (withdrawn): The ECMP system of claim 16 wherein said electrically-conductive filler component is selected from the group consisting of graphite particles, metal particles, metal-coated metal particles, metal-coated non-metal particles, and mixtures thereof.

Claim 20 (withdrawn): The ECMP system of claim 16 wherein said electrically-conductive filler component comprises graphite particles.

Claim 21 (withdrawn): The ECMP system of claim 16 wherein said electrically-conductive filler component comprises tin particles.

Claim 22 (withdrawn): The ECMP system of claim 16 wherein said polymeric component comprises a urethane polymer or copolymer.

Claim 23 (withdrawn): The ECMP system of claim 16 wherein the compound comprises, by total weight of the components (a) and (b), between about 25-95% of the electrically-conductive filler component.

Claim 24 (withdrawn): The ECMP system of claim 16 wherein the electrically-conductive filler component comprises particles having a mean average particle size of between about 0.01-10 mil (0.25-250 μm).

Claim 25 (withdrawn): The ECMP system of claim 16 wherein the compound has an electrical volume resistivity of not greater than about 1 $\Omega\text{-cm}$.

Claim 26 (withdrawn): The ECMP system of claim 16 wherein the admixture further comprises:

(c) a resin filler component forming a second discrete phase within said continuous phase, said second discrete phase being substantially free of said electrically-conductive filler component.

Claim 27 (withdrawn): The ECMP system of claim 26 wherein the compound comprises, by total weight of the components (a), (b), and (c), between about 1-10% of the resin filler component.

Claim 28 (withdrawn): The ECMP system of claim 26 wherein the resin filler component comprises particles having a mean average particle size of between about 0.08-2 mil (2-50 μm).

Claim 29 (withdrawn): The ECMP system of claim 26 wherein said resin filler component comprises particles of one or more thermoplastic resins.

Claim 30 (withdrawn): The ECMP system of claim 16 wherein said article further comprises a carrier, said layer of said electrically-conductive compound being supported on said carrier.

Claim 31 (withdrawn): The ECMP system of claim 30 wherein said carrier comprises a sheet of an electrically-conductive mesh.

Claim 32 (currently amended): An electrochemical mechanical polishing (ECMP) method for processing a surface of a workpiece, said method comprising the steps of:

(a) providing a polishing article, the article comprising an electrically-conductive compound which is formed into a layer having a processing surface, said compound comprising an admixture which comprises:

(I) a polymeric component forming a continuous phase in said layer; and
(II) an electrically-conductive filler component comprising tin particles forming a first discrete phase within said continuous phase,

(b) electrically connecting the layer of step (a) to the workpiece; and

(c) applying an electrical bias between the workpiece and the layer, the bias being capable of activating an electrochemical reaction, and the compound of the layer exhibiting an overpotential for the activation of said reaction.

Claim 33 (original): The ECMP method of claim 32 wherein the layer of step (a) has a processing surface, and wherein the method further comprising the additional step following step (a) of:

disposing the surface of the workpiece against the processing surface of the layer.

Claim 34 (original): The ECMP method of claim 33 wherein said overpotential is at least about 1 V.

Claim 35 (cancelled)

Claim 36 (cancelled)

Claim 37 (cancelled)

Claim 38 (original): The ECMP method of claim 33 wherein said polymeric component comprises a urethane polymer or copolymer.

Claim 39 (original): The ECMP method of claim 33 wherein the compound comprises, by total weight of the components (I) and (II), between about 25-95% of the electrically-conductive filler component.

Claim 40 (original): The ECMP method of claim 33 wherein the electrically-conductive filler component comprises particles having a mean average particle size of between about 0.01-10 mil (0.25-250 μm).

Claim 41 (original): The ECMP method of claim 33 wherein the compound has an electrical volume resistivity of not greater than about 1 $\Omega\text{-cm}$.

Claim 42 (previously presented): The ECMP method of claim 33 wherein the admixture further comprises:

(III) a resin filler component forming a second discrete phase within said continuous phase, said second discrete phase being solid and substantially free of said electrically-conductive filler component.

Claim 43 (original): The ECMP method of claim 42 wherein the compound comprises, by total weight of the components (I), (II), and (III), between about 1-10% of the resin filler component.

Claim 44 (original): The ECMP method of claim 42 wherein the resin filler component comprises particles having a mean average particle size of between about 0.08-2 mil (2-50 μm).

Claim 45 (original): The ECMP method of claim 42 wherein said resin filler component comprises particles of one or more thermoplastic resins.

Claim 46 (original): The ECMP method of claim 33 wherein said article further comprises a carrier, said layer of said electrically-conductive compound being supported on said carrier.

Claim 47 (original): The ECMP method of claim 46 wherein said carrier comprises a sheet of an electrically-conductive mesh.